



MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3	
Semiconductor Device Type: CB / NB / TT (C6X) 003 SOT-23 Matte Tin										
Basic Substance		CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	6.62 (mg) Total	Mold Compound	% of Total Weight	79.8
Silica, vitreous		60676-86-0	Mold Compound	67.830	5.630	678,300	Silica, vitreous60676-86-085.00 Epoxy ResinTrade Secret6.13 Phenolic ResinTrade Secret6.13 Epoxy, Cresol Novolac29690-82-22.45 Carbon Black1333-86-40.30 Total100.00			
Epoxy Resin (No bromine, No diantimony trioxide)		Trade Secret	Mold Compound	4.888	0.406	48,878				
Phenolic Resin (No Br / CL SbO ₃ , No diantimony trioxide)		Trade Secret	Mold Compound	4.888	0.406	48,878				
Epoxy, Cresol Novolac		29690-82-2	Mold Compound	1.955	0.162	19,551				
Carbon Black		1333-86-4	Mold Compound	0.239	0.020	2,394				
Copper		7440-50-8	Lead Frame	10.031	0.833	100,314	0.87 (mg) Total Lead Frame % of Total Weight 10.5 Copper7440-50-895.54 Iron7439-89-62.35 Silver7440-22-41.91 Zinc7440-66-60.13 Phosphorous7723-14-00.08 Total100.00			
Iron		7439-89-6	Lead Frame	0.247	0.020	2,468				
Silver		7440-22-4	Lead Frame	0.200	0.017	2,000				
Zinc		7440-66-6	Lead Frame	0.013	0.001	131				
Phosphorous		7723-14-0	Lead Frame	0.009	0.001	87				
Silver (Ag)		7440-22-4	Die Attach	0.563	0.047	5,625	0.06 (mg) Total Die Attach % of Total Weight 0.75 Silver (Ag)7440-22-475.00 Modified Epoxy Resin13561-08-514.00 Diglycidylether of bisphenol-F54208-63-87.50 Modified Amine827-43-03.50 Total100.00			
Modified Epoxy Resin		13561-08-5	Die Attach	0.105	0.009	1,050				
Diglycidylether of bisphenol-F		54208-63-8	Die Attach	0.056	0.005	563				
Modified Amine		827-43-0	Die Attach	0.026	0.002	263				
Silicon		7440-21-3	Chip (Die)	7.500	0.623	75,000				
Gold		7440-57-5	Wire Bond	0.200	0.017	2,000	Doped Silicon 7440-21-3 100.00 Total100.00			
Tin		7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	0.104	12,500				
TOTALS:				100.000	8.300	1,000,000				
0.0083 g Total Mass										
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)										
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.										
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.										
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/										
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.										
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table										
8.300							100.00			